

Inclined Rotary Plasma Enhanced Chemical Vapor Deposition Pecvd Equipment Tube Furnace Machine

Item Number: KT-PED



Introduction

Upgrade your coating process with PECVD coating equipment. Ideal for LED, power semiconductors, MEMS and more. Deposits high-quality solid films at low temps.

Learn More

Sample holder Gas purge	Size	1-6 inches
	Rotate speed	0-20rpm adjustable
	Heating temperature	≤800°C
	Control accuracy	±0.5°C SHIMADEN PID Controller
	Flow meter	MASS FLOWMETER CONTROLLER (MFC)
	Channels	4 channels
Vacuum chamber	Cooling method	Circulating water cooling
	Chamber size	Φ500mm X 550mm
	Observation port	Full view port with baffle
	Chamber material	316 Stainless steel
	Door type	Front open type door
	Cap material	304 Stainless steel
	Vacuum pump port	CF200 flange
	Gas inlet port	φ6 VCR connector
Plasma power	Source power	DC power or RF power
	Coupling mode	Inductively coupled or plate capacitive
	Output power	500W—1000W
	Bias power	500v
Vacuum pump	Pre- pump	15L/S Vane vacuum pump
	Turbo pump port	CF150/CF200 620L/S-1600L/S
	Relief port	KF25
	Pump speed	Vane pump:15L/s[Turbo pump:1200l/s[]1600l/s
	Vacuum degree	≤5×10-5Pa
	Vacuum sensor	lonization/resistance vacuum gauge/film gauge
System	Electric power supply	AC 220V /380 50Hz



5kW Rated power

200kg Weight